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August 2003



FDP6030L/FDB6030L

N-Channel Logic Level PowerTrench^o MOSFET

General Description

This N-Channel Logic Level MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers.

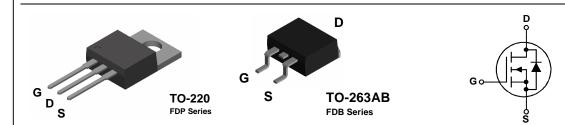
These MOSFETs feature faster switching and lower gate charge than other MOSFETs with comparable $R_{\text{DS(ON)}}$ specifications.

The result is a MOSFET that is easy and safer to drive (even at very high frequencies), and DC/DC power supply designs with higher overall efficiency.

It has been optimized for low gate charge, low $R_{\text{DS}(\text{ON})}$ and fast switching speed.

Features

- 48 A, 30 V $R_{DS(ON)} = 13 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$ $R_{DS(ON)} = 17 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$
- Critical DC electrical parameters specified at elevated temperature
- High performance trench technology for extremely low $R_{\text{DS}(\text{ON})}$
- 175°C maximum junction temperature rating



Absolute Maximum Ratings T_A=25°C unless otherwise noted

| Symbol | Parameter | Ratings | Units |
|-----------------------------------|--|-------------|-------|
| V _{DSS} | Drain-Source Voltage | 30 | V |
| V _{GSS} | Gate-Source Voltage | ± 20 | V |
| ID | Drain Current – Continuous (Note 1) | 48 | А |
| | – Pulsed | 150 | |
| P _D | Total Power Dissipation @ $T_c = 25^{\circ}C$ | 52 | W |
| | Derate above 25°C | 0.3 | W/°C |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | -65 to +175 | °C |

Thermal CharacteristicsReJCThermal Resistance, Junction-to-Case2.9°C/WReJAThermal Resistance, Junction-to-Ambient62.5

Package Marking and Ordering Information

| | Device Marking | Device | Reel Size | Tape width | Quantity |
|---|----------------|----------|-----------|------------|-----------|
| | FDB6030L | FDB6030L | 13" | 24mm | 800 units |
| _ | FDP6030L | FDP6030L | Tube | n/a | 45 |

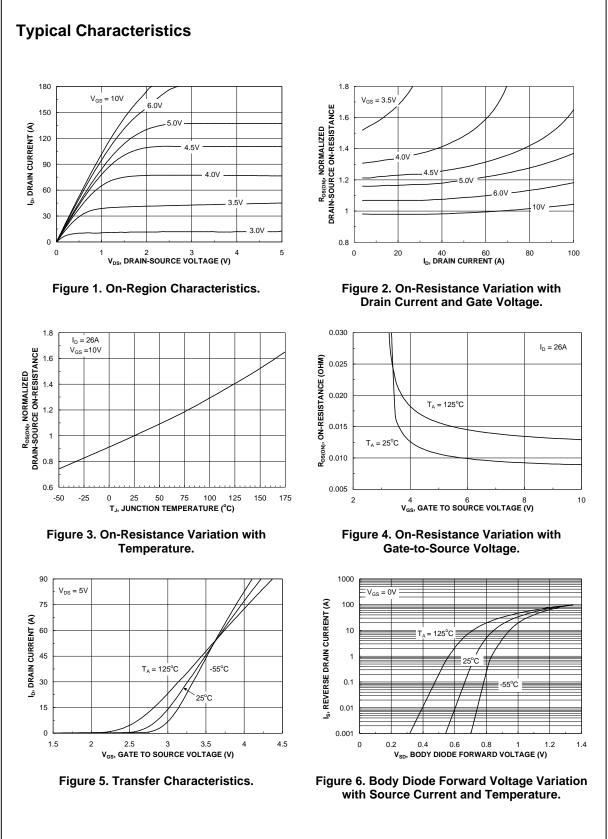
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| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|--|---|---|-----|------|----------|------------|
| Drain-So | Durce Avalanche Ratings (Note | 21) | | | | |
| E _{AS} | Single Pulse Drain-Source Avalanche Energy | $V_{DD} = 15 \text{ V}, I_D = 26 \text{ A}$ | | | 100 | mJ |
| I _{AS} | Maximum Drain-Source Avalanche | | | | 26 | A |
| Off Char | Current acteristics | | | | | |
| BV _{DSS} | Drain–Source Breakdown Voltage | $V_{1} = 0 V_{1} = 250 \mu$ | 30 | | | V |
| ΔBV_{DSS} | Breakdown Voltage Temperature | $V_{GS} = 0 \text{ V}, \qquad I_D = 250 \mu\text{A}$ $I_D = 250 \mu\text{A}, \text{ Referenced to } 25^\circ\text{C}$ | 30 | 23 | | w mV/°C |
| <u>ΔT</u> J | Coefficient Zero Gate Voltage Drain Current | $V_{DS} = 24 V$, $V_{GS} = 0 V$ | | | 1 | |
| | Gate-Body Leakage | $V_{DS} = 24 V, V_{GS} = 0 V$ $V_{GS} = \pm 20 V, V_{DS} = 0 V$ | | | ± 100 | μA nA |
| | , , | $v_{\rm GS} = \pm 20$ v, $v_{\rm DS} = 0$ v | 1 | | ± 100 | |
| | acteristics (Note 2) | | | 4.0 | <u> </u> | |
| V _{GS(th)} | Gate Threshold Voltage | $V_{DS} = V_{GS}, \qquad I_D = 250 \ \mu A$ | 1 | 1.9 | 3 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate Threshold Voltage Temperature Coefficient | $I_D = 250 \ \mu\text{A}$, Referenced to 25°C | | -5 | | mV/°C |
| R _{DS(on)} | Static Drain–Source On– | $V_{GS} = 10 \text{ V}, I_D = 26 \text{ A}$ | | 7.9 | 13 | |
| | Resistance | $V_{GS} = 4.5 V$, $I_D = 21 A$ | | 10.2 | 17 | mΩ |
| | On–State Drain Current | V_{GS} = 10 V, I_D = 26 A, T_J =125°C V_{GS} = 10 V, V_{DS} = 10 V | 60 | 13.0 | 20 | A |
| D(on) | Forward Transconductance | $V_{\rm ds} = 10 V,$ $V_{\rm Ds} = 10 V$ $V_{\rm Ds} = 10 V,$ $I_{\rm D} = 26 \text{ A}$ | 00 | 68 | | S |
| g _{FS} | | $v_{DS} = 10v$, $i_D = 20 A$ | | 00 | | 5 |
| | Characteristics | | | 10-0 | | _ |
| C _{iss} | Input Capacitance | $V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ | | 1250 | | pF |
| Coss | Output Capacitance | f = 1.0 MHz | | 330 | | pF |
| C _{rss} | Reverse Transfer Capacitance | | | 155 | | pF |
| R _G | Gate Resistance | $V_{\text{GS}} = 15 \text{ mV}, f = 1.0 \text{ MHz}$ | | 1.3 | | Ω |
| Switchin | g Characteristics (Note 2) | | | | | |
| t _{d(on)} | Turn–On Delay Time | $V_{DD} = 15V, \qquad I_D = 1 \text{ A},$ | | 11 | 20 | ns |
| tr | Turn–On Rise Time | $V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$ | | 12 | 22 | ns |
| t _{d(off)} | Turn–Off Delay Time | 7 | | 29 | 46 | ns |
| t _f | Turn–Off Fall Time | 7 | | 12 | 21 | ns |
| Qg | Total Gate Charge | $V_{DS} = 15 V$, $I_D = 26 A$, | | 13 | 18 | nC |
| Q _{gs} | Gate-Source Charge | $V_{GS} = 5 V$ | | 3.9 | | nC |
| Q _{gd} | Gate–Drain Charge | | | 5.2 | | nC |
| Drain-S | ource Diode Characteristics | and Maximum Ratings | | | | |
| I _S | Maximum Continuous Drain–Source | | | | 48 | Α |
| V _{SD} | Drain–Source Diode Forward Voltage | $V_{GS} = 0 V$, $I_S = 26 A$ (Note 1) | | 0.92 | 1.3 | V |
| t _{rr} | Diode Reverse Recovery Time | I _F = 26 A, | | 26 | | nS |
| Q _{rr} | Diode Reverse Recovery Charge | $I_F = 26 \text{ A},$ $d_{iF}/d_t = 100 \text{ A}/\mu\text{s}$ | | 15 | | nC |

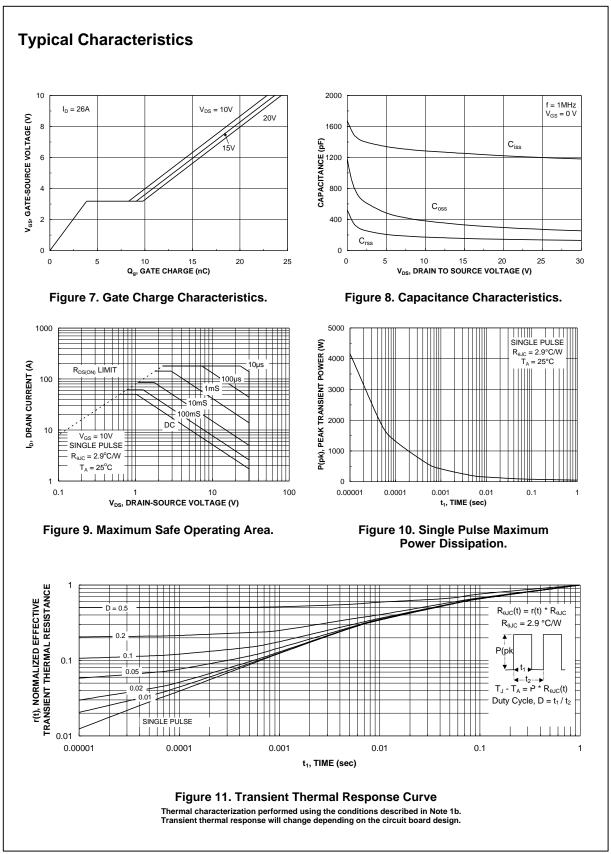
1. Calculated continuous current based on maximum allowable junction temperature.

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

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|---------------------------|---|
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